


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE						
<div>Application Number: 09/912844</div> <div>Confirmation Number: 5915</div> <div>First Named Applicant: Thomas Haverstock</div> <div>Attorney Docket Number:</div> <div>Search string: (6521466 or 6541278 or 6546946 or 6550484 or 6558475 or 6561213 or 6561220 or 6561481 or 6561767 or 6564826 or 5217043 or 20020001929).pn.</div> <div></div>							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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<input checked="" type="checkbox"/>	1	6521466	2002-02-18	Castrucci	B1		
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US Published Applications							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
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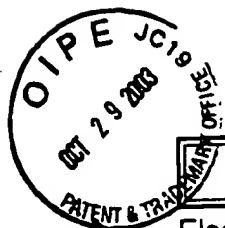
Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 4 out of a total of 4 electronic filings. Fee has been paid in previous electronic filing.

Signature

Examiner Name	Date
Ram Karkar	11-26-03



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<div>Application Number: 09/912844</div> <div>Confirmation Number: 5915</div> <div>First Named Applicant: Maximilian Biberger</div> <div>Attorney Docket Number:</div> <div>Search string: (5900107 or 5904737 or 5932100 or 5934991 or 5981399 or 5989342 or 6005226 or 6017820 or 6029371 or 6037277 or 6053348 or 6056008 or 6077053 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6203582 or 6216364 or 6239038 or 6241825 or 6251250 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or 6464790).pn.</div>							
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init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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M	2	5904737	1999-05-18	Preston et al.			
M	3	5932100	1999-08-03	Yager et al.			
M	4	5934991	1999-08-10	Rush			
M	5	5981399	1999-11-09	Kawamura et al.			
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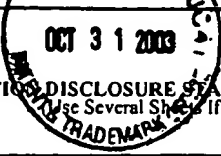

Remarks

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Examiner Name	Date
<i>Ra</i>	11-26-03

FORM PTO-1449 (Modified)				U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: SSI-00501		Serial No.: 09/912,844	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)						Applicants: Maximilian A. Biberger et al.			
(37 CFR § 1.98(b))						Filing Date: July 24, 2001		Group Art Unit: 1763	
FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS									
		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation		
							Yes	No	
22	AA	CN 1399790 A	02/26/03	China	H01L	21/00		X	
22	AB	DE 36 08 783 A1	09/17/87	Germany	C30B	25/12		X	
22	AC	DE 198 60 084 A1	07/06/00	Germany	H01L	21/3213		X	
22	AD	EP 0 244 951 A2	11/11/87	EPO	H01L	21/00		X	
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22	AF	EP 0 453 867 A1	10/30/91	EPO	F16K	51/02		X	
22	AG	EP 0 572 913 A1	12/08/93	EPO	B01D	11/02		X	
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22	AK	FR 1,499,491	09/18/67	France	F16K			X	
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22	AP	JP 11-200035	07/27/99	Japan	C23C	14/34		X	
22	AQ	JP 56-142629	11/07/81	Japan	H01L	21/205		X	
22	AR	JP 60-238479	11/27/85	Japan	C23C	14/56		X	
22	AS	JP 60-246635	12/06/85	Japan	H01L	21/302		X	
22	AT	JP 61-231166	10/15/86	Japan	C23C	14/24		X	
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22	AV	JP 63-303059	12/09/88	Japan	C23C	14/22		X	
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22	AX	WO 87/07309	12/03/87	PCT	C23C	16/00		X	
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22	BE	WO 02/16051 A2	02/28/02	PCT	B05D			X	
22	BF	WO 03/030219 A2	10/04/03	PCT	H01L			X	
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22	BI								
Examiner: 					Date Considered: 11-26-03				
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									

FORM PTO-1449
(Modified)U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: SSI-00501

Serial No.: 09/912,844

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
(Also Patent Office Form PTO-1449, Use Additional Sheets If Necessary)

Applicants: Maximilian A. Biberger et al.

Filing Date: July 24, 2001

Group Art Unit: 1763

(37 CFR § 1.98(b))

FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS

		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
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Examiner:

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EXAMINER:

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Attorney Docket Number:							
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Inlt	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 1 out of a total of 4 electronic filings.

Signature

Examiner Name	Date
<i>R</i>	11-26-03

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

Stylesheet Version v1.8.0

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE		
Application Number:	09/912844	*09/912844*	
Confirmation Number:	5915		
First Named Applicant:	Maximilian Biberger		
Attorney Docket Number:			
Search string:	(5193560 or 5195878 or 5213485 or 5221019 or 5222876 or 5224504 or 5236669 or 5240390 or 5243821 or 5246500 or 5251776 or 5280693 or 5285352 or 5288333 or 5339844 or 5370741 or 5412958 or 5433334 or 5447294 or 5503176 or 5505219 or 5509431 or 5571330 or 5589224 or 5621982 or 5629918 or 5644855 or 5649809 or 5656097 or 5669251 or 5702228 or 5706319 or 5746008),pn.		
US Patent Documents			
Note: Applicant is not required to submit a paper copy of cited US Patent Documents			
Int.	Cite.No.	Patent No.	Date
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2	2	5195878	1993-03-23
3	3	5213485	1993-05-25
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Examiner Name	Date
<i>[Signature]</i>	11-26-03

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Remarks

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v1.8.0

Title of Invention		HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE					
Application Number:		09/912844			*09/912844*		
Confirmation Number:		5915					
First Named Applicant:		Maximilian Biberger					
Attorney Docket Number:							
Search string:		(5900107 or 5904737 or 5932100 or 5934991 or 5981399 or 5989342 or 6005226 or 6017820 or 6029371 or 6037277 or 6053348 or 6056008 or 6077053 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6203582 or 6216364 or 6239038 or 6241825 or 6251250 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or 6464790).pn.					
US Patent Documents							
Note: Application is not required to submit a paper copy of cited US Patent Documents							
Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
<input checked="" type="checkbox"/>	1	5900107	1999-05-04	Murphy et al.			
<input checked="" type="checkbox"/>	2	5904737	1999-05-18	Preston et al.			
<input checked="" type="checkbox"/>	3	5932100	1999-08-03	Yager et al.			
<input checked="" type="checkbox"/>	4	5934991	1999-08-10	Rush			
<input checked="" type="checkbox"/>	5	5981399	1999-11-09	Kawamura et al.			
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Information Disclosure Statement

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Page 3 of 3

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Examiner Name	Date
Ram	11-26-03

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

Stylesheet Version v1.8.0

Title of
Invention**HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR
SUBSTRATE**

Application Number: 09/912844 *09/912844*
Confirmation Number: 5915
First Named Applicant: Thomas Haverstock
Attorney Docket Number:
Search string: (6521466 or 6541278 or 6546946 or 6550484 or 6558475 or
6561213 or 6561220 or 6561481 or 6561767 or 6564826 or
5217043 or 20020001929),pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Ink	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
22	1	6521466	2002-02-18	Castrucci	B1		
22	2	6541278	2003-04-01	Morita et al.	B1		
22	3	6546946	2003-04-15	Dunmire	B1		
22	4	6550484	2003-04-22	Gopinath et al.	B1		
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22	6	6561213	2003-05-13	Wang et al.	B1		
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22	9	6561767	2003-05-13	Biberger et al.	B1		
22	10	6564826	2003-05-20	Shen	B1		
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US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

Ink	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
22	1	20020001929	2002-01-03	Biberger et al.	A1		

Remarks

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The current electronic filing contains part 4 out of a total of 4 electronic filings. Fee has been
paid in previous electronic filing.

Signature

Examiner Name	Date
<i>Res</i>	11-26-03